IN THE CLAIMS

Please amend the claims as follows:

Claims 1-25 (Cancelled)

Claim 26 (Currently Amended): An electronic device comprising:

an electronic part or die joined to a heat spreader joined to a heat sink,

wherein said heat spreader comprises a sealed structure encapsulating a condensable fluid therein which can repeatedly evaporate and condense to transport heat; and

wherein said electronic device comprises means for joining the die or electronic part to the heat spreader so ~~wherein the die or electronic part is joined to the heat spreader in a manner~~ that ~~no significant~~ thermal stress that causes separation of the die or electronic part and the heat spreader does not occur ~~is caused between the heat spreader and die or electronic part by heat generated by the die or electronic part~~.

Claim 27 (Currently Amended): The electronic device of Claim 26,

wherein the die or electronic part and heat spreader components are selected to have about the same coefficients of thermal expansion such that they do not generate ~~significant~~ thermal stress sufficient to separate ~~between the gradient layer and~~ the die or electronic part ~~or~~ and the heat spreader.

Claim 28 (Withdrawn): The electronic device of Claim 27, wherein the electronic part or die is joined to the heat spreader via a grading layer which has three layers, wherein the layer in contact with the electronic part or die has a coefficient of thermal expansion approximate to that of the electronic part or die and the layer in contact with the heat spreader

has a coefficient of thermal expansion approximate to that of the heat spreader, and these two layers are separated by an intermediate layer having a coefficient of thermal expansion between that of the electronic part or die and the heat spreader.

Claim 29 (Withdrawn): The electronic device of Claim 26, wherein the die or electronic part is joined to the heat spreader via a graphite layer.

Claim 30 (Withdrawn): The electronic device of Claim 26, wherein the graphite layer is joined to the die or electronic part and the heat spreader with an adhesive or solder.

Claim 31 (Withdrawn): The electronic device of Claim 26, wherein the graphite layer is joined to the heat spreader by a diffused junction method.

Claim 32 (Withdrawn): The electronic device of Claim 26, wherein the heat spreader has a lubricating material buried in one face.

Claim 33 (Withdrawn): The electronic device of Claim 26,

wherein the heat spreader is made of aluminum and has an anodized face having fine cracks which are and filled with molybdenum sulfide as the lubricating material.

Claim 34 (Previously Presented): The electronic device of Claim 26, wherein said die or electronic part comprises silicon.

Claim 35 (Previously Presented), The electronic device of Claim 26, wherein said heat spreader is invar (nickel steel) which comprises 0.4% Mn, 0.2% C, 36% Ni, and the remainder Fe.

Claim 36 (Previously Presented): The electronic device of Claim 26, wherein said heat spreader is aluminum nitride.

Claim 37 (Previously Presented): The electronic device of Claim 26, which is an MPU.

Claim 38 (Previously Presented): The electronic device of Claim 26, which is an image processor.